

- **21:3 Data Channel Compression at up to 196 Million Bytes per Second Throughput**
- **Suited for SVGA, XGA, or SXGA Data Transmission From Controller to Display With Very Low EMI**
- **21 Data Channels Plus Clock In Low-Voltage TTL Inputs and 3 Data Channels Plus Clock Out Low-Voltage Differential Signaling (LVDS) Outputs**
- **Operates From a Single 3.3-V Supply and 89 mW (Typ)**
- **Ultralow-Power 3.3-V CMOS Version of the SN75LVDS84. Power Consumption About One Third of the 'LVDS84**
- **Packaged in Thin Shrink Small-Outline Package (TSSOP) With 20 Mil Terminal Pitch**
- **Consumes Less Than 0.54 mW When Disabled**
- **Wide Phase-Lock Input Frequency Range: 31 MHz to 75 MHz**
- **No External Components Required for PLL**
- **Outputs Meet or Exceed the Requirements of ANSI EIA/TIA-644 Standard**
- **SSC Tracking Capability of 3% Center Spread at 50-kHz Modulation Frequency**
- **Improved Replacement for SN75LVDS84 and NSC's DS90CF363A 3-V Device**
- **Available in Q-Temp Automotive High Reliability Automotive Applications Configuration Control / Print Support Qualification to Automotive Standards**

DGG PACKAGE
(TOP VIEW)

| | | | |
|-----------------|----|----|---------------------|
| D4 | 1 | 48 | D3 |
| V _{CC} | 2 | 47 | D2 |
| D5 | 3 | 46 | GND |
| D6 | 4 | 45 | D1 |
| GND | 5 | 44 | D0 |
| D7 | 6 | 43 | NC |
| D8 | 7 | 42 | LVDSGND |
| V _{CC} | 8 | 41 | Y0M |
| D9 | 9 | 40 | Y0P |
| D10 | 10 | 39 | Y1M |
| GND | 11 | 38 | Y1P |
| D11 | 12 | 37 | LVDSV _{CC} |
| D12 | 13 | 36 | LVDSGND |
| NC | 14 | 35 | Y2M |
| D13 | 15 | 34 | Y2P |
| D14 | 16 | 33 | CLKOUTM |
| GND | 17 | 32 | CLKOUTP |
| D15 | 18 | 31 | LVDSGND |
| D16 | 19 | 30 | PLLGND |
| D17 | 20 | 29 | PLLV _{CC} |
| V _{CC} | 21 | 28 | PLLGND |
| D18 | 22 | 27 | SHTDN |
| D19 | 23 | 26 | CLKIN |
| GND | 24 | 25 | D20 |

NC – Not Connected

description

The SN75LVDS84A and SN65LVDS84AQ FlatLink transmitters contain three 7-bit parallel-load serial-out shift registers, and four low-voltage differential signaling (LVDS) line drivers in a single integrated circuit. These functions allow 21 bits of single-ended LVTTL data to be synchronously transmitted over 3 balanced-pair conductors for receipt by a compatible receiver, such as the SN75LVDS82 or SN75LVDS86/86A.

When transmitting, data bits D0 – D20 are each loaded into registers of the 'LVDS84A upon the falling edge. The internal PLL is frequency-locked to CLKIN and then used to unload the data registers in 7-bit slices. The three serial streams and a phase-locked clock (CLKOUT) are then output to LVDS output drivers. The frequency of CLKOUT is the same as the input clock, CLKIN.



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SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

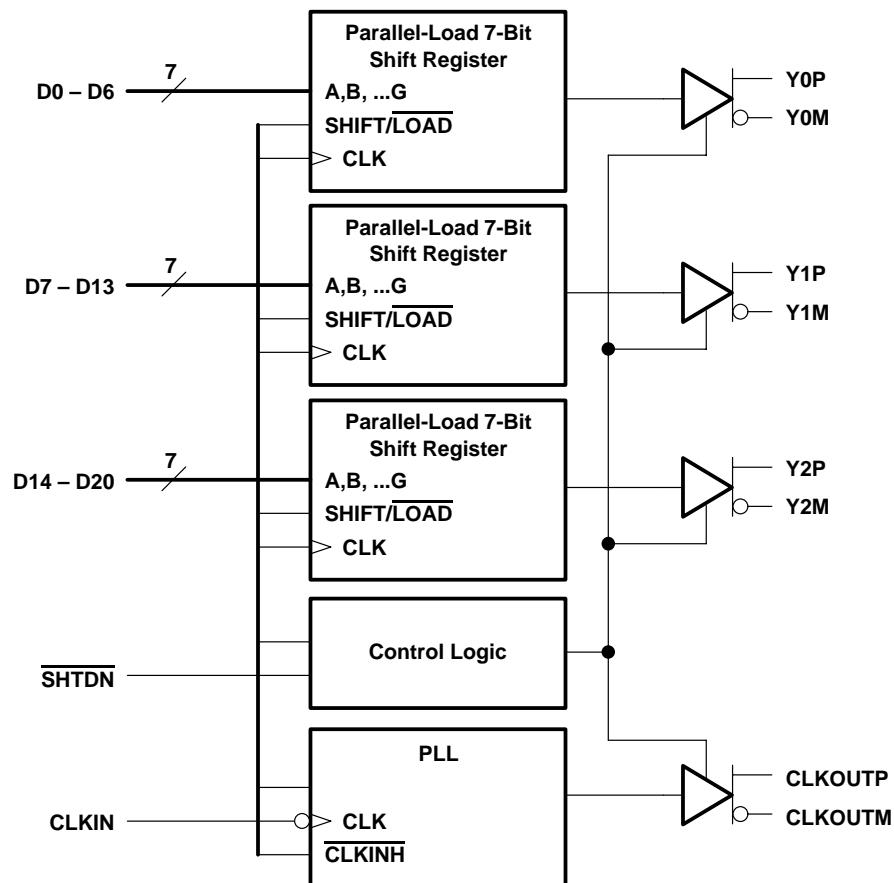
SLLS354E – MAY 1999 – REVISED JANUARY 2001

description (continued)

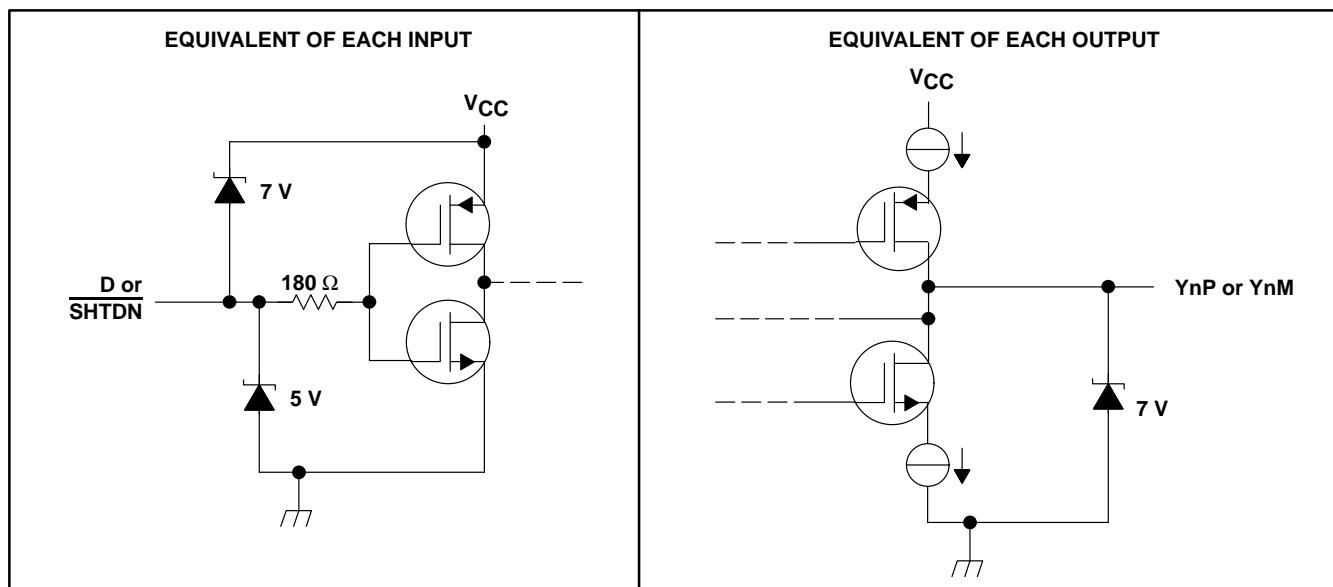
The 'LVDS84A requires no external components and little or no control. The data bus appears the same at the input to the transmitter and output of the receiver with the data transmission transparent to the user(s). The only user intervention is the possible use of the shutdown/clear (SHTDN) active-low input to inhibit the clock and shut off the LVDS output drivers for lower power consumption. A low-level on this signal clears all internal registers to a low level.

The SN75LVDS84A is characterized for operation over ambient free-air temperatures of 0°C to 70°C. The SN65LVDS84AQ is characterized for operation over the full Automotive temperature range of –40°C to 125°C.

functional block diagram



schematics of input and output



absolute maximum ratings over operating free-air temperature (unless otherwise noted)

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the GND terminals.

DISSIPATION RATING TABLE

| PACKAGE | $T_A \leq 25^\circ\text{C}$ POWER RATING | DERATING FACTOR [‡] ABOVE $T_A = 25^\circ\text{C}$ | $T_A = 70^\circ\text{C}$ POWER RATING | $T_A = 125^\circ\text{C}$ POWER RATING |
|---------|---|--|--|---|
| DGG | 1637 mW | 13.1 mW/ $^\circ\text{C}$ | 1048 mW | 327 mW |

† This is the inverse of the junction-to-ambient thermal resistance when board mounted and with no air flow.

recommended operating conditions

| | MIN | NOM | MAX | UNIT |
|---------------------------------------|--------------|-----|-----|----------|
| Supply voltage, V_{CC} | 3 | 3.3 | 3.6 | V |
| High-level input voltage, V_{IH} | 2 | | | V |
| Low-level input voltage, V_{IL} | | | 0.8 | V |
| Differential load impedance, Z_L | 90 | | 132 | Ω |
| Operating free-air temperature, T_A | SN75LVDS84A | 0 | 70 | °C |
| | SN65LVDS84AQ | -40 | 125 | |

SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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timing requirements

| | | MIN | NOM | MAX | UNIT |
|----------|---|-----------|-----------|------|------|
| t_c | Input clock period | 13.3 | t_c | 32.4 | ns |
| t_w | Pulse duration, high-level input clock | 0.4 t_c | 0.6 t_c | | ns |
| t_t | Transition time, input signal | | | 5 | ns |
| t_{su} | Setup time, data, D0 – D20 valid before CLKIN↓ (see Figure 2) | 3 | | | ns |
| t_h | Hold time, data, D0 – D20 valid after CLKIN↓ (see Figure 2) | 1.5 | | | ns |

electrical characteristics over recommended operating conditions (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TY [†] | MAX | UNIT | |
|------------------|---|---|------------------------------|------------------------|----------|----|
| V_{IT} | Input threshold voltage | | 1.4 | | V | |
| $ V_{OD} $ | Differential steady-state output voltage magnitude | $R_L = 100 \Omega$, See Figure 3 | 247 | 454 | mV | |
| $\Delta V_{OD} $ | Change in the steady-state differential output voltage magnitude between opposite binary states | | | 50 | mV | |
| $V_{OC(SS)}$ | Steady-state common-mode output voltage | $R_L = 100 \Omega$, See Figure 3 | 1.125 | 1.375 | V | |
| $V_{OC(PP)}$ | Peak-to-peak common-mode output voltage | | 80 | 150 | mV | |
| I_{IH} | High-level input current | $V_{IH} = V_{CC}$ | SN75LVDS84A SN65LVDS84AQ | 20 25 | μA | |
| I_{IL} | Low-level input current | $V_{IL} = 0$ | | ± 10 | μA | |
| I_{OS} | Short-circuit output current | $V_O(Y_n) = 0$ | | -6 | ± 24 | mA |
| I_{OD} | | $V_{OD} = 0$ | | -6 | ± 12 | mA |
| I_{OZ} | High-impedance output current | $V_O = 0$ to V_{CC} | | ± 10 | μA | |
| $I_{CC(AVG)}$ | Quiescent supply current (average) | Disabled, All inputs at GND | SN75LVDS84A SN65LVDS84AQ | 15 15 150 170 | μA | |
| | | Enabled, $R_L = 100 \Omega$ (4 places) Gray-scale pattern (see Figure 4) | $f = 65$ MHz $f = 75$ MHz | 27 30 35 38 | mA | |
| | | Enabled, $R_L = 100 \Omega$, (4 places) Worst-case pattern (see Figure 5) | $f = 65$ MHz $f = 75$ MHz | 28 31 36 39 | | |
| C_I | Input capacitance | | | 2 | | pF |

[†] All typical values are at $V_{CC} = 3.3$ V, $T_A = 25^\circ C$.

switching characteristics over recommended operating conditions (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|-------------------|---|--------------|------------------------|------------------------|------|
| t_{d0} | $t_c = 15.38 \text{ ns} (\pm 0.2\%)$, Input clock jitter < 50 ps‡, See Figure 6 | | -0.2 | 0.2 | ns |
| t_{d1} | | | $\frac{1}{7}t_c - 0.2$ | $\frac{1}{7}t_c + 0.2$ | |
| t_{d2} | | | $\frac{2}{7}t_c - 0.2$ | $\frac{2}{7}t_c + 0.2$ | |
| t_{d3} | | | $\frac{3}{7}t_c - 0.2$ | $\frac{3}{7}t_c + 0.2$ | |
| t_{d4} | | | $\frac{4}{7}t_c - 0.2$ | $\frac{4}{7}t_c + 0.2$ | |
| t_{d5} | | | $\frac{5}{7}t_c - 0.2$ | $\frac{5}{7}t_c + 0.2$ | |
| t_{d6} | | | $\frac{6}{7}t_c - 0.2$ | $\frac{6}{7}t_c + 0.2$ | |
| $t_{sk(o)}$ | $t_n - \frac{n}{7}t_c$ | | -0.2 | 0.2 | ns |
| t_{d7} | $t_c = 15.38 \text{ ns} (\pm 0.2\%)$, Input clock jitter < 50 ps‡, See Figure 6 | | | 2.7 | ns |
| | $t_c = 13.33 \text{ ns} \sim 32.25 \text{ ns} (\pm 0.2\%)$, Input clock jitter < 50 ps‡, See Figure 6 | | 1 | 4.5 | |
| $\Delta t_{c(o)}$ | $t_c = 15.38 + 0.308 \sin(2\pi 500E3t) \pm 0.05 \text{ ns}$, See Figure 7 | | | ± 62 | ps |
| | $t_c = 15.38 + 0.308 \sin(2\pi 3E6t) \pm 0.05 \text{ ns}$, See Figure 7 | | | ± 121 | |
| t_w | | | $\frac{4}{7}t_c$ | | ns |
| t_t | Transition time, differential output voltage (t_r or t_f) | See Figure 3 | 700 | 1500 | ps |
| t_{en} | Enable time, <u>SHTDN</u> ↑ to phase lock (Yn valid) | See Figure 8 | | 1 | ms |
| t_{dis} | Disable time, <u>SHTDN</u> ↓ to off state (CLKOUT low) | See Figure 9 | | 6.5 | ns |

† All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ |Input clock jitter| is the magnitude of the change in the input clock period.

§ Output clock jitter is the change in the output clock period from one cycle to the next cycle observed over 15000 cycles.

SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

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PARAMETER MEASUREMENT INFORMATION

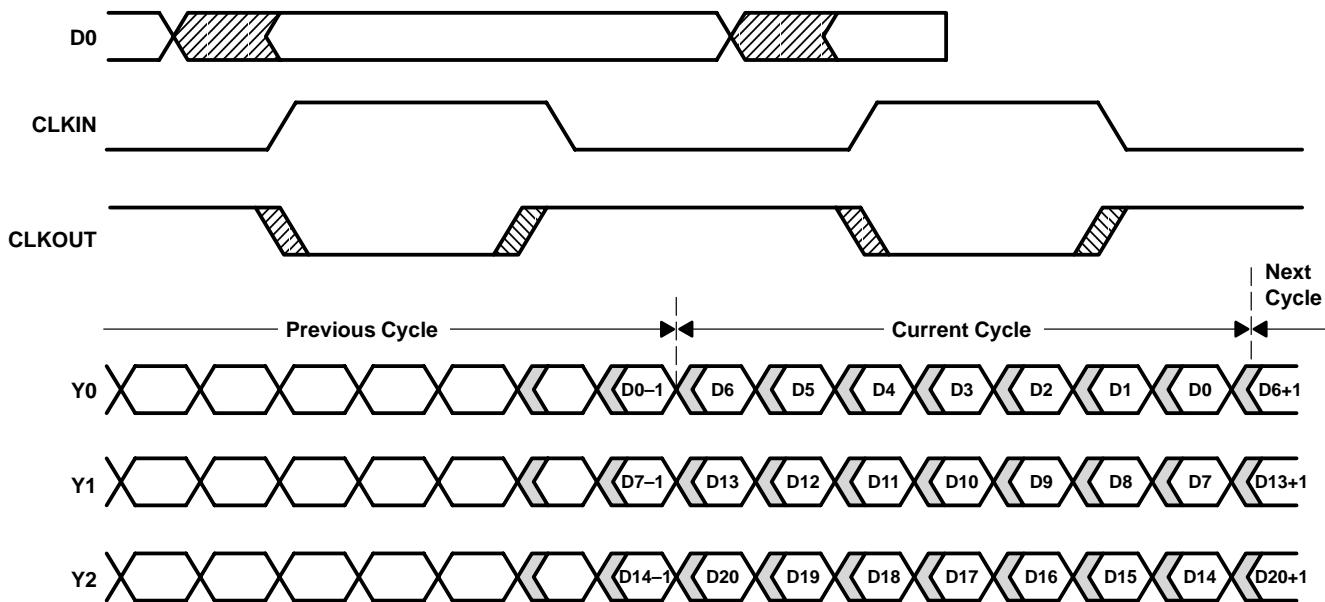
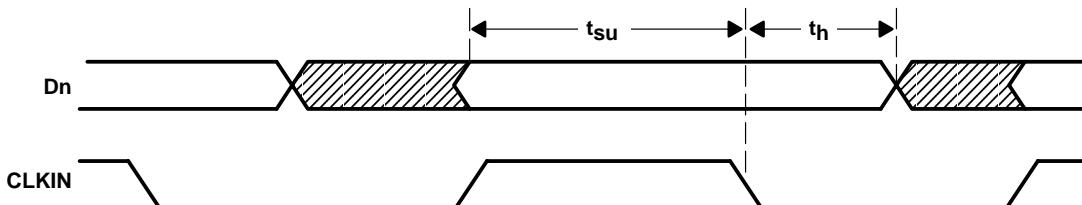
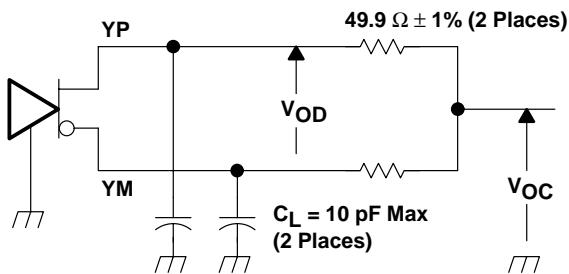


Figure 1. Typical Load and Shift Sequences



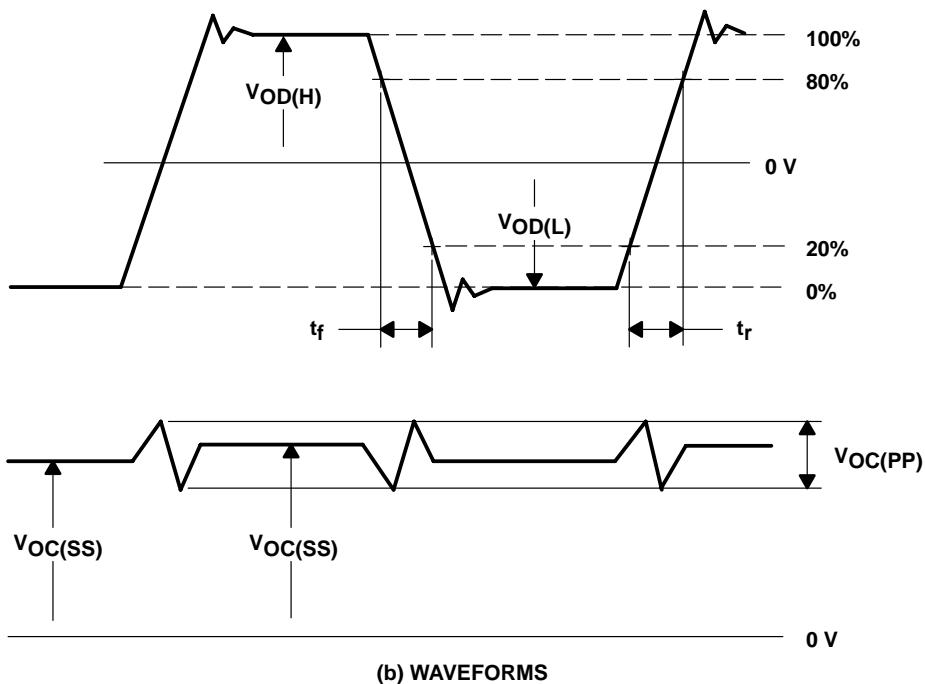
NOTE A: All input timing is defined at 1.4 V on an input signal with a 10%-to-90% rise or fall time of less than 5 ns.

Figure 2. Setup and Hold Time Definition



NOTE A: The lumped instrumentation capacitance for any single-ended voltage measurement is less than or equal to 10 pF. When making measurements at YP or YM, the complementary output is similarly loaded.

(a) SCHEMATIC



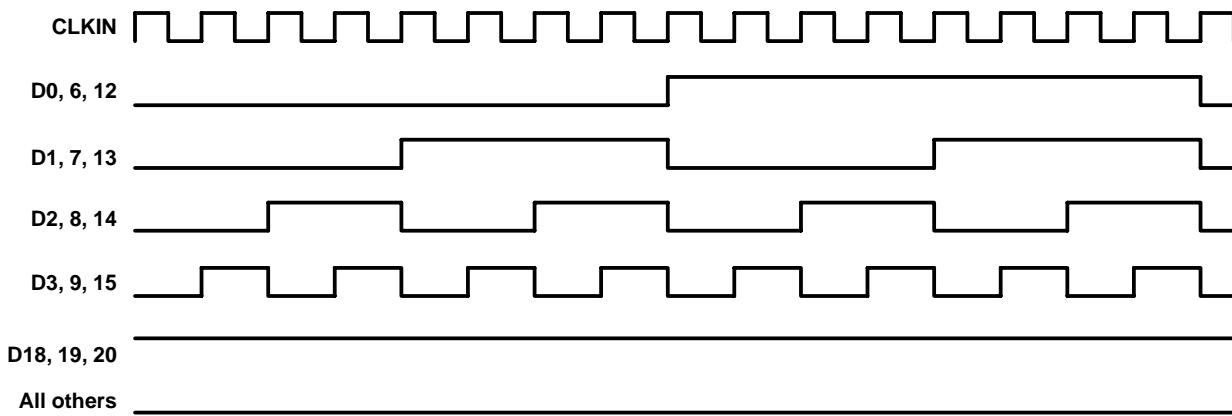
(b) WAVEFORMS

Figure 3. Test Load and Voltage Definitions for LVDS Outputs

SN75LVDS84A, SN65LVDS84AQ FLATLINK™ TRANSMITTER

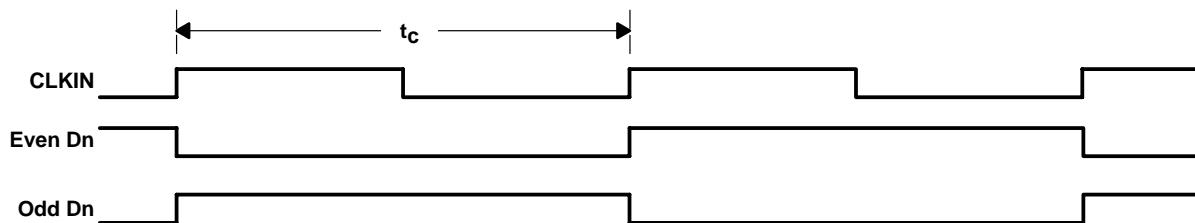
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PARAMETER MEASUREMENT INFORMATION



NOTES: A. The 16-grayscale test-pattern test device power consumption for a typical display pattern.
B. $V_{IH} = 2$ V and $V_{IL} = 0.8$ V

Figure 4. 16-Grayscale Test-Pattern Waveforms



NOTES: A. The worst-case test pattern produces nearly the maximum switching frequency for all of the LVDS outputs.
B. $V_{IH} = 2$ V and $V_{IL} = 0.8$ V

Figure 5. Worst-Case Test-Pattern Waveforms

PARAMETER MEASUREMENT INFORMATION

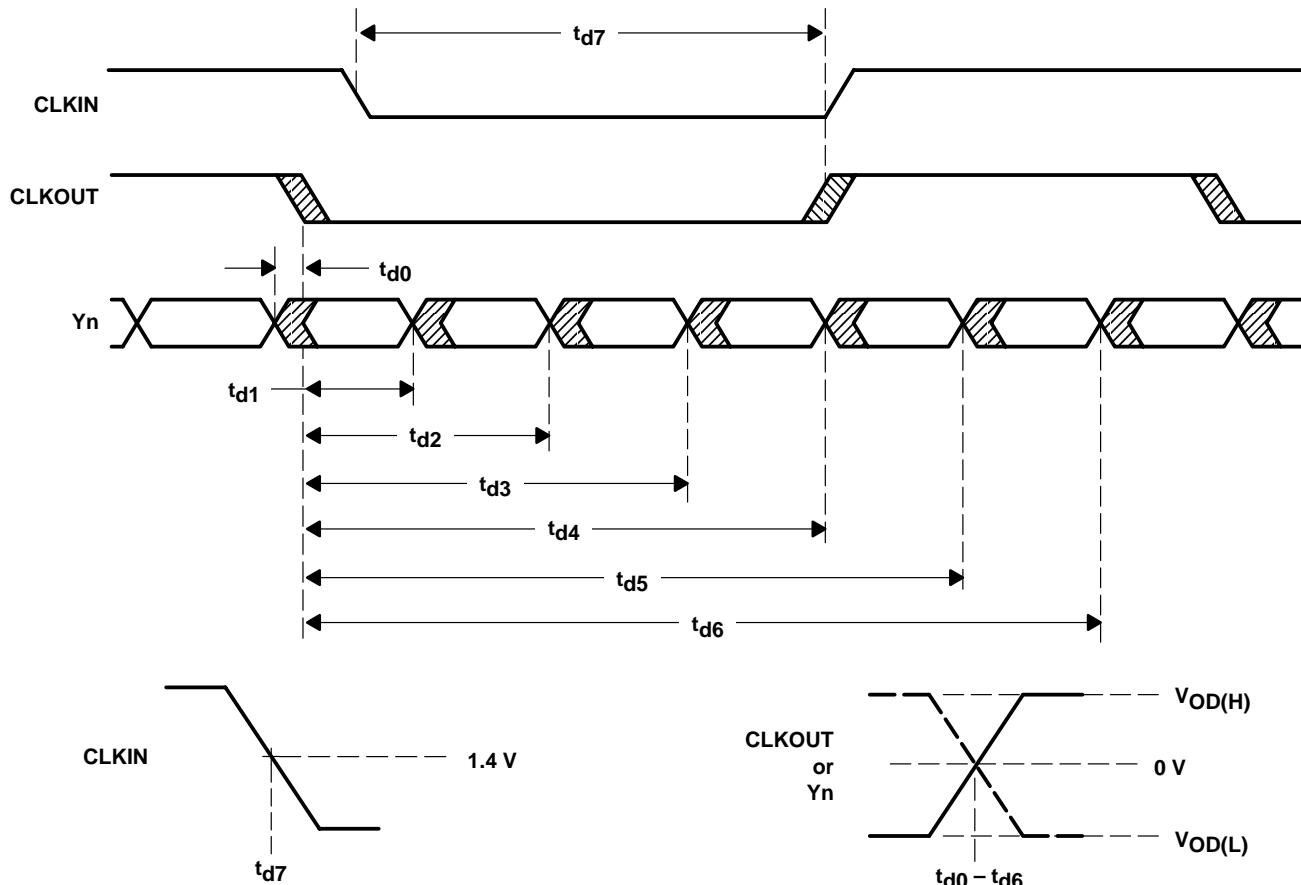


Figure 6. Timing Definitions

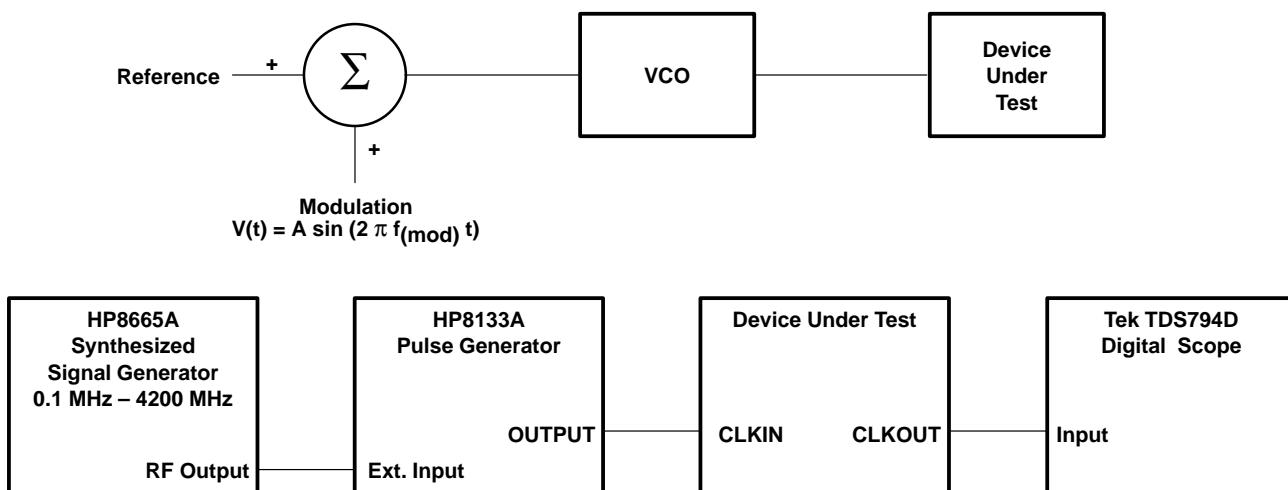


Figure 7. Clock Jitter Test Setup

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TYPICAL CHARACTERISTICS

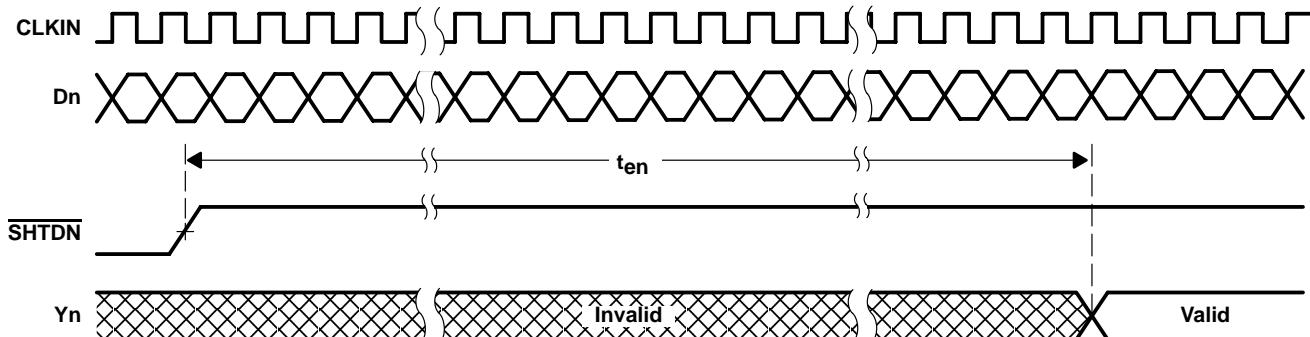


Figure 8. Enable Time Waveforms

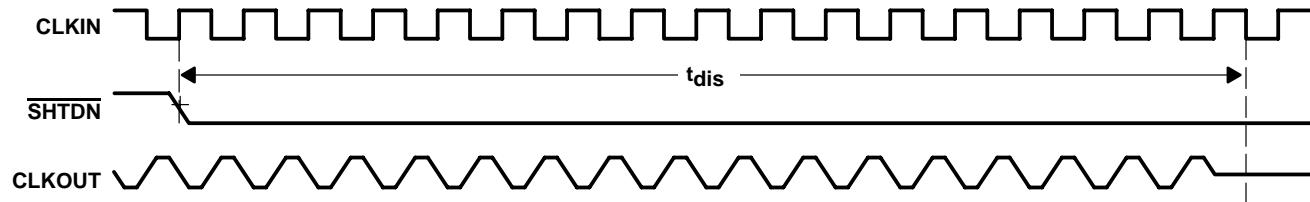


Figure 9. Disable Time Waveforms

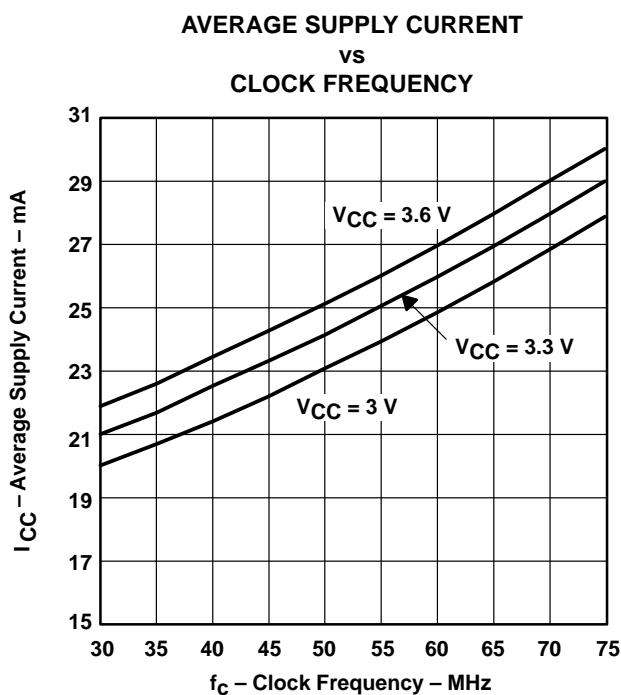


Figure 10. Grayscale Input Pattern

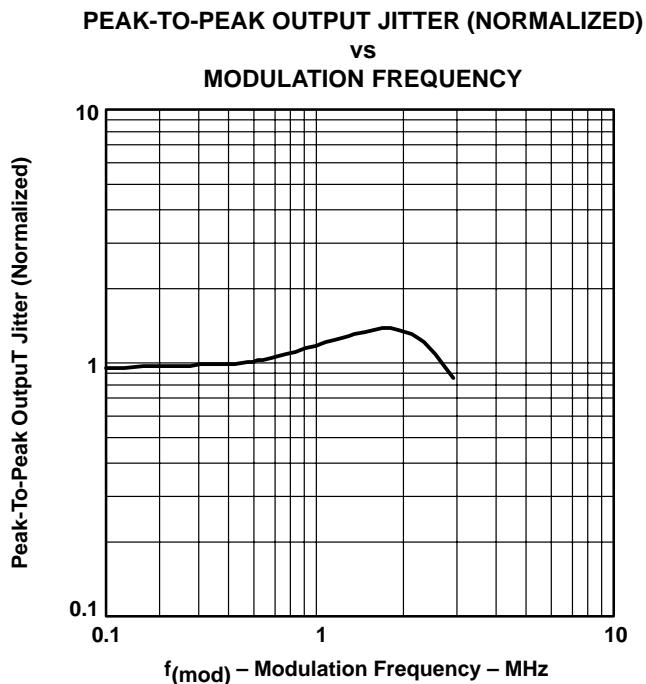
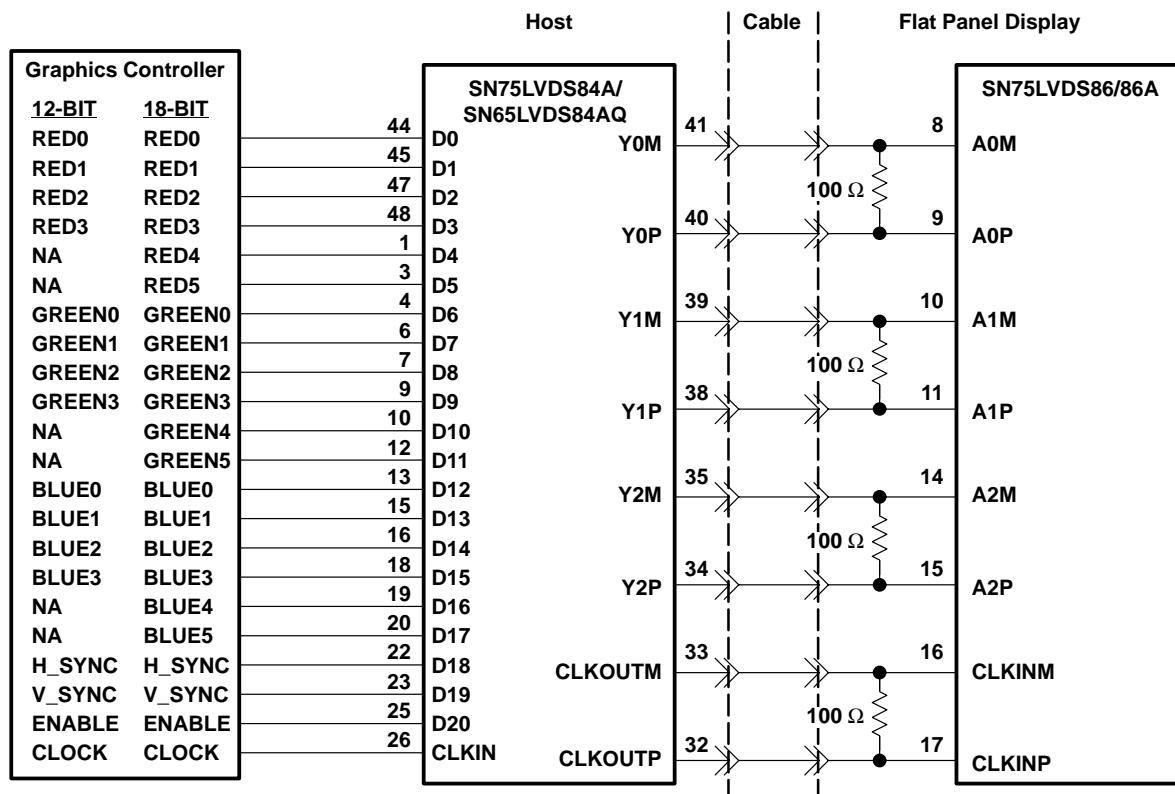


Figure 11. Output Period Jitter vs Modulation Frequency

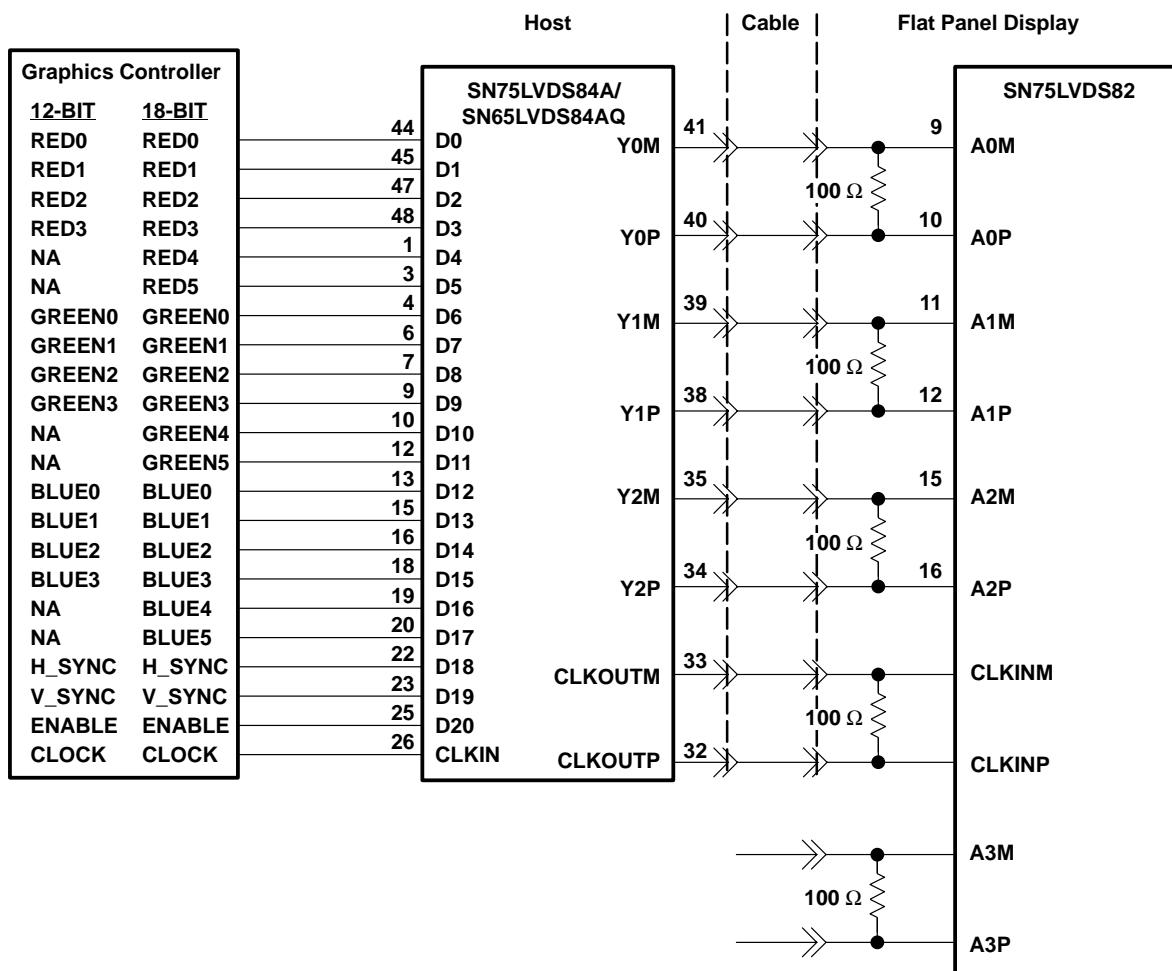
APPLICATION INFORMATION



NOTES: A. The five 100-Ω terminating resistors are recommended to be 0603 types.
B. NA – not applicable, these unused inputs should be left open.

Figure 12. Color Host to LCD Panel Application

APPLICATION INFORMATION



NOTES: A. The four 100- Ω terminating resistors are recommended to be 0603 types.
B. NA – not applicable, these unused inputs should be left open.

Figure 13. 18-Bit Color Host to 24-Bit LCD Display Panel Application

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|-------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN65LVDS84AQDGG | ACTIVE | TSSOP | DGG | 48 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN65LVDS84AQDGGR | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN75LVDS84ADGG | ACTIVE | TSSOP | DGG | 48 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN75LVDS84ADGGG4 | ACTIVE | TSSOP | DGG | 48 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN75LVDS84ADGGR | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN75LVDS84ADGGRG4 | ACTIVE | TSSOP | DGG | 48 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

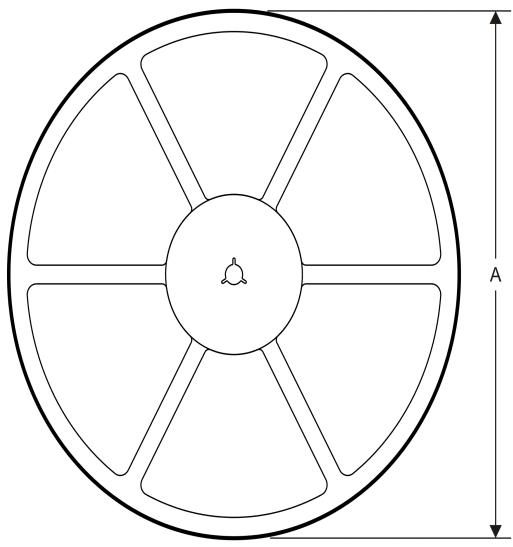
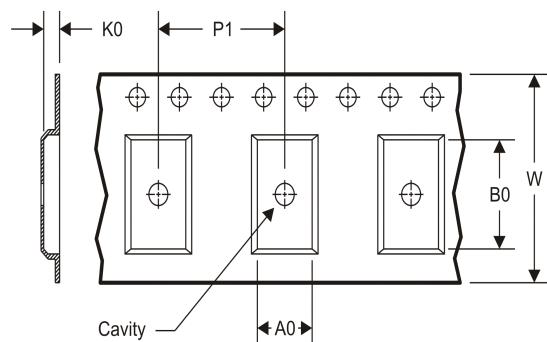
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

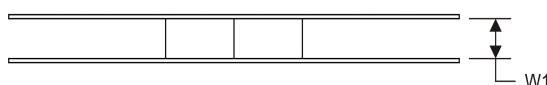
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |


TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN65LVDS84AQDGGR | TSSOP | DGG | 48 | 2000 | 330.0 | 24.4 | 8.6 | 15.8 | 1.8 | 12.0 | 24.0 | Q1 |
| SN75LVDS84ADGGR | TSSOP | DGG | 48 | 2000 | 330.0 | 24.4 | 8.6 | 15.8 | 1.8 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

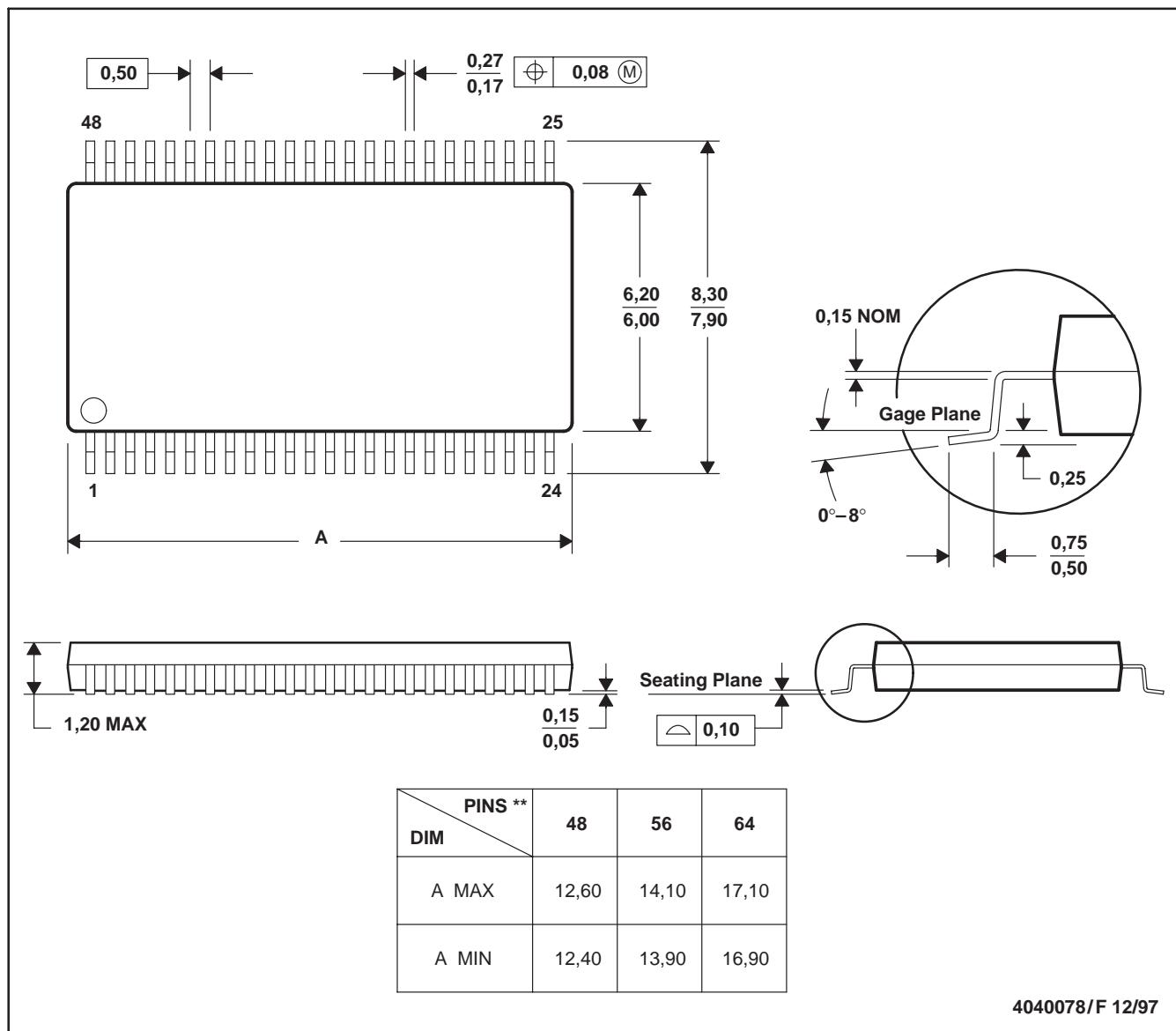

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN65LVDS84AQDGGR | TSSOP | DGG | 48 | 2000 | 367.0 | 367.0 | 45.0 |
| SN75LVDS84ADGGR | TSSOP | DGG | 48 | 2000 | 367.0 | 367.0 | 45.0 |

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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